# SILICON TRANSISTOR

# AUDIO FREQUENCY AMPLIFIER, SWITCHING PNP SILICON EPITAXIAL TRANSISTORS

## FEATURES

NEC

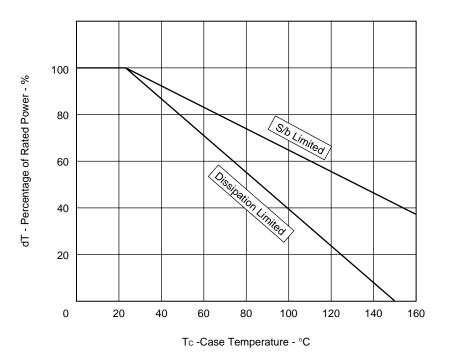
<ul> <li>Low V<sub>CE(sat)</sub> V<sub>CE(sat)</sub> = -0.15 V Max (@Ic/IB = 1.0 A/5</li> <li>High DC Current Gain hEF = 150 to 600 (@V<sub>CE</sub> = -2.0 V, Ic =</li> </ul>	,	
ABSOLUTE MAXIMUM RATINGS		
Maximum Voltage and Current (T <sub>A</sub> = 25	°C)	
Collector to Base Voltage	Vсв0	–30 V
Collector to Emitter Voltage	Vce0	–30 V
Emitter to Base Voltage	Veb0	–6.0 V
Collector Current (DC)	IC(DC)	–5.0 A
Collector Current (Pulse)*	C(Pulse	) —10 A
Base Current (DC)	B(DC)	–2.0 A
* PW $\leq$ 10ms, Duty Cycle $\leq$ 10 %		
Maximum Power Dissipation		
Total Power Dissipation (Tc = 25 °C)	Р⊤	10 W
Total Power Dissipation (T <sub>A</sub> = 25 $^{\circ}$ C)	Р⊤	1.0 W
Maximum Temperature		
Junction Temperature	Tj	150 °C
Storage Temperature	Tstg	–55 to 150 $^\circ\text{C}$

### PACKAGE DIMENSIONS in millimeters (inches) 2.8 MAX. 8.5 MAX. (0.334 MAX.) (0.110 MAX.) 3.8 ± 0.2 (0.149) $\phi 3.2 \pm 0.2 \ (\phi 0.126)$ 126) MAX 12.0 MAX. ò (0.472 N 0 1 2 3 1.2 2.5 ± 0.2 (0.098) 13.0 MIN. (0.512 MIN.) (0.047)0.55+0.08 (0.021) 0.8+0.08 (0.031)1.2 2.3 2.3 (0.047)(0.090) (0.090) 1. Emitter 2. Collector connected to mounting plane 3. Base

# ELECTRICAL CHARACTERISTICS (TA = 25 °C)

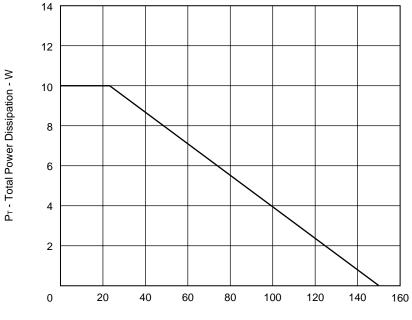
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Collector Cutoff Currnet	Ісво	$V_{CB} = -30 \text{ V}, \text{ Ie} = 0$			-100	nA
Emitter Cutoff Current	Іево	$V_{EB} = -6.0 V$ , Ic = 0			-100	nA
DC Current Gain	hfe1	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -1.0 \text{ A}$	150		600	
DC Current Gain	hFE2	$V_{CE} = -2.0 \text{ V}, \text{ Ic} = -4.0 \text{ A}$	50			_
Collector Saturation Voltage	VCE(sat)1	$I_{C} = -1.0 \text{ A}, I_{B} = -50 \text{ mA}$		-0.09	-0.15	V
Collector Saturation Voltage	VCE(sat)2	Ic = -2.0 A, I <sub>B</sub> = -0.1 A		-0.17	-0.25	V
Collector Saturation Voltage	VCE(sat)3	$I_{C} = -4.0 \text{ A}, I_{B} = -0.2 \text{ A}$		-0.32	-0.50	V
Base Saturation Voltage	VBE(sat)	$I_{C} = -1.0 \text{ A}, I_{B} = -0.1 \text{ A}$		-0.87	-1.50	V
Gain Bandwidth Product	fт	$V_{CE} = -10 \text{ V}, \text{ Ie} = -50 \text{ mA}$		95		MHz
Output Capacitance	Cob	$V_{\text{CB}} = -10 \text{ V}, \text{ I}_{\text{E}} = 0, \text{ f} = 1 \text{ MHz}$		100		pF

The information in this document is subject to change without notice.

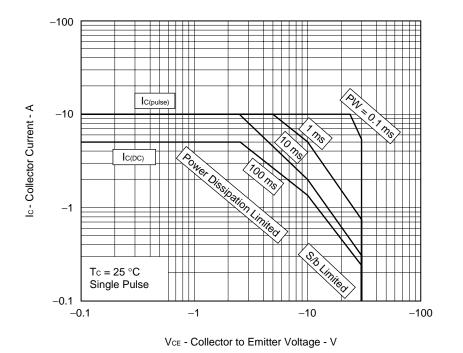


DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA

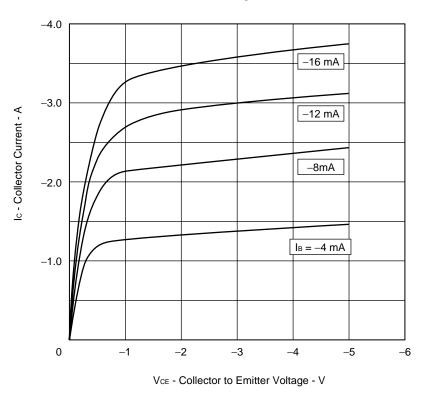
TOTAL POWER DISSIPATION vs. CASE TENPERATURE



Tc -Case Temperature - °C

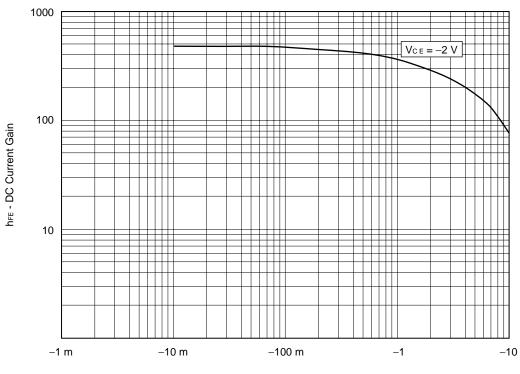


FORWARD BIAS SAFE OPERATING AREA

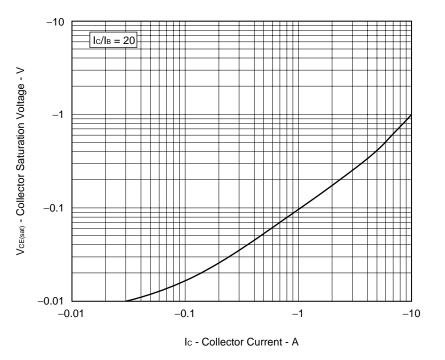


Collector to Emitter Voltage vs Collector Current



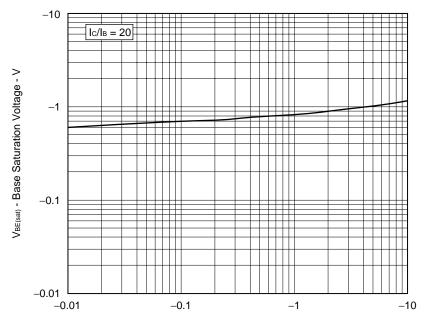


Ic - Collector Current - A

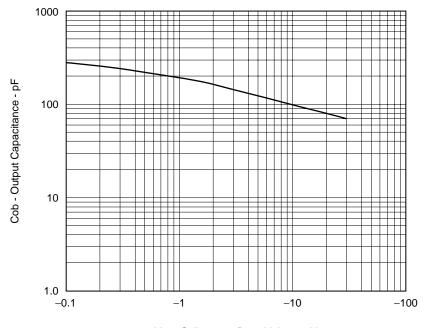


COLLECTOR SATURATION VOLTAGE vs COLLECTOR CURRENT

### BASE SATURATION VOLTAGE vs COLLECTOR CURRENT



Ic - Collector Current - A



OUTPUT CAPACITANCE vs COLLECTOR TO BASE VOLTAGE

 $V_{\mbox{\tiny CB}}$  - Collector to Base Voltage - V

# REFERENCE

Document Name	Document No.		
NEC semiconductor device reliability/quality control system	TEI-1202		
Quality grade on NEC semiconductor devices	IEI-1209		
Semiconductor device mounting technology manual	C10535E		
Semiconductor device package manual	C10943X		
Guide to quality assurance for semiconductor devices	MEI-1202		
Semiconductor selection guide	X10679E		

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Anti-radioactive design is not implemented in this product.

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Datasheets for electronics components.